LITE-ON SEMICONDUCTOR

Customer Notification of Product/Process Changes

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*PCN	No.:	P16006
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*Issued Date: Mar/18/2016

*Subject: Change clip joint method

*Effective date: Apr /30/2016

Affected category: F3-D	*Affected family: FB345D & FB3A45D
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Change Item	☐ Material ■ Design ☐ Process ■	Others	
Impact Item	1. Product P/N ∶ ☐ Yes ■ No 3	3. Label : ☐ Yes ■ No	
	2. Marking : ☐ Yes ■ No	1. Other items : ☐ Yes ■ No	
Other Related Item	N/A		
Change Purpose	Change clip joint method to improve the soldering yield		
	Before Change	After Change	
Description of Change	Flat joint method	Card slot joint method	
Relevant	☐ Electrical Test Report (as the attachment)		
Verification	☐ Mechanical Test Report (as the attachment) ☐Others (ex. Impacted part list) (as the attachment)		
Report			
Other Related . Report	N/A		
Sample availability	■Yes □No		
Customer	Approve		
Approval	☐ Disapprove		
Customer Requirement			
(ex. Last Buy			
requirement)			

Note:

- (1.) If you need sample(s) or any question, please contact with our Salesperson within 30day
- (2.) PCN for customer notification/response, ref. JEDEC No. 46 sec 3.2.3 to implement.

Quality Assurance

FIV-0A 101-2